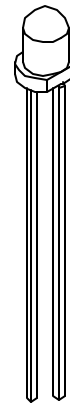
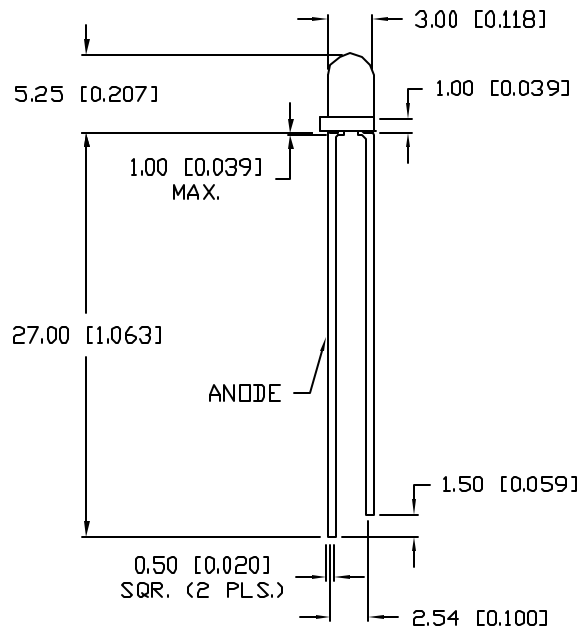
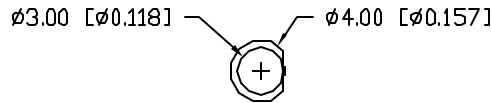


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PART NUMBER
SSL-LX3054ID

REV.
D

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	REDRAWN.	9.1.93
B	UPDATED SPECS.	8.11.94
C	UPADTED SAFE OPER SPECS.	1.20.95
D	E.C.N. #10BRDR. & REDRAWN IN 3D.	4.16.01



ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^{\circ}\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		635		nm	
FORWARD VOLTAGE		2.0	2.5	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_f=100\mu\text{A}$
<input checked="" type="checkbox"/> AXIAL INTENSITY		40		md	$I_f=20\text{mA}$
<input checked="" type="checkbox"/> VIEWING ANGLE		60		2x theta	
EMITTED COLOR:	RED				
EPOXY LENS FINISH:	RED DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
<input checked="" type="checkbox"/> PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
<input checked="" type="checkbox"/> POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.6	mW/°C
<input checked="" type="checkbox"/> OPERATING, STORAGE TEMP.	-40 TO +85	°C
<input checked="" type="checkbox"/> SOLDERING TEMP.	+260	°C
<input checked="" type="checkbox"/> 2.0mm FROM BODY		3 SEC. MAX

* $t < 10\mu\text{s}$

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN= ^{+0.00} _{-0.00} DECIMAL PRECISION MAX.= ^{+0.00} _{-0.00} DECIMAL PRECISION

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290 E. HELEN ROAD
PALATINE, IL 60067-6976
PHONE: +1.847.359.2790
US WEB: www.lumex.com
TW WEB: www.lumex.com.tw

T-3mm (T-1) 635nm RED LED,
RED DIFFUSED LENS.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY:

BC

CHECKED BY:

APPROVED BY:

DATE: 8.9.94

PAGE: 1 OF 1

SCALE: N/A